

ABSTRACT

A method of bonding substrates and devices having bonded substrates are disclosed. The method of bonding substrates includes depositing a layer of bonding substrate material onto a bonding surface of a first substrate. A bonding site density
5 of at least one of the layer of bonding substrate material or a bonding surface of a second substrate is increased, and the bonding surface of the first substrate having the layer of bonding substrate material is bonded to the bonding surface of the second substrate.